

# **Automatic Cleaning Machine Hydro-clean LDS Linear Direct Spray**



## **Cleaning Application**

- eaning Application

  Removing all kinds of solder residues
  Cleaning of micromechanical components
  Removing contamination from handling
  and board manufacturing, FOD
  Cleaning highly populated electronic
  assemblies with low standoff such as BGA,
  FC, CSP, BTC, QFN, MELF
  Cleaning of power electronics
  Cleaning sensitive electronic devices
  One side misprints on complex assemblies
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- Cleaning before conformal coating and wire bonding

#### **Unique Advantage**

- Fully automatic spray-in-air closed loop zero drain system
- Triple capacity configuration
- Linear direct spray for equal washing of entire surface
- 100% filtration of entire DI water
- Optional triple rinse
- Hot air knife direct dry technology
- Illuminated glass door chamber for visual process control
- All process steps with up to 5 substeps

- for highest flexibility
- Wide range of standard and customized PCBA fixtures
- Clamping for all types of stencils
- Up to 3 fully separated liquid loops
- Low consumption of chemicals and water
- Proportional level sensors in all processes
- Outstanding options of water utilization



# **Versions by Application**

Wash + Rinse I + Rinse II + Drying PCBA after soldering, PCBA before coating, power electronics, micromechanics

#### **Filtration Options**

Zero drain concept-close loop or open loop can be set by software

Special filtration strategy for the highest flow

First rinse filtration fully separated from second rinse filtration

#### **Technical Parameter**

Machine dimension (L × W × H)	1 900 x 1 700 x 1930 mm
Weight (without liquid)	1000kg
Machine noisiness	LAeq <70 dB
Power supply voltage	3x 400/230 V, 50Hz
Power input	12-30KVA
Volume of tank	70L
Working range	3×80×800×800mm
Washing - pressure on the nozzles max/min	2.5-3bar
Washing – max. flow	200L/min
Rinsing - pressure on the nozzles max/min	1.5-2bar
Rinsing - max. flow	180L/min

# **Adjustable Parameter**

Steel mesh washing time	0-99 min.
Steer mesh washing time	0 99 111111.
PCBA+Misprints washing time	0-99min.
Washing medium temperature	Room temp 60 °C
Rinsing temperature	Room temp 60 °C
Drying temperature	Room temp 90°C
Drying time	0-99min
Specific conductance	0-99 μS/cm (2 <sup>nd</sup> rinse)